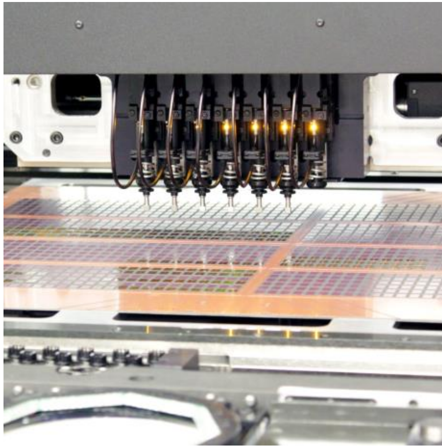
Universal Instruments Corporation
Ultra-thin Die Assembly for FHE Systems PC 2.0



The focus of the proposed work group is to clearly define the most relevant techniques for attaching very thin (30 to 75 micron) integrated circuits to flexible films and to utilize Universal's background IP and pre-existing technology to complete the design and build of a die handler to present these devices to a Universal placement machine for attachment. Universal will be responsible for the mechanical design of the end effector tooling which contacts the silicon device, utilizing our background IP and pre-existing technology, and our partnering organizations will provide the much needed insight into their vision for IC interconnect based on real world applications. Our partners in this effort include Binghamton University, GE Global Research, I3 Electronics, and Lockheed Martin.